Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L2	1541	@ad<="20040601" and (257/700).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 08:51
L3	1795	@ad<="20040601" and (257/737).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 08:33
L4	135	@ad<="20040601" and (257/709).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 08:34
L5	2667	@ad<="20040601" and (257/686-688).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 08:34
L6	3680	@ad<="20040601" and (257/778-780).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 10:43
L7	3407	@ad<="20040601" and (257/787).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 08:36
L8	526	@ad<="20040601" and (257/685).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 08:37
L9	786	@ad<="20040601" and (257/675).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 11:11
L10	1747	@ad<="20040601" and (257/718-719).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 08:39
L11	2049	@ad<="20040601" and (257/723).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 08:39

L12	528	@ad<="20040601" and (257/725-726).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 08:40
L13	689	@ad<="20040601" and (257/796).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 08:40
L14	0	@ad<="20040601" and 'flip chip' and 'ball grid array' and "'capacitor'."	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 08:41
L15	811	@ad<="20040601" and 'flip chip' and 'BGA' and 'capacitor'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 08:42
L16	133	@ad<="20040601" and 'flip chip' and 'BGA' and 'decoupling' with 'capacitor'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 09:45
L17	2201	@ad<="20040601" and (257/678).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 08:51
L18	0	@ad<="20040601" and 'FCBGA' and 'heat spreader' and 'resion'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 09:11
L19	225	@ad<="20040601" and 'Flip chip' and 'BGA' and 'heat spreader' and 'resin'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 09:11
L20	10	@ad<="20040601" and 'FCBGA' and 'heat spreader' and 'resin'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 09:14
L21	4	@ad<="20040601" and 'FCBGA' and 'heat spreader' and 'resin' and 'capacitor'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 09:19
L22	20	@ad<="20040601" and 'FCBGA' and 'heat spreader'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 09:18

L23	72	@ad<="20040601" and 'FCBGA' and 'resin'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 09:18
L24	28	@ad<="20040601" and 'FCBGA' and 'capacitor'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 09:18
L25	156	@ad<="20040601" and 'FCBGA'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 09:19
L26	1	"6037677".PN.	USPAT; USOCR	OR	ON	2005/04/07 09:36
L27	404	@ad<="20040601" and 'flip chip' and 'BGA' and 'semiconductor chip' with ('via' or 'through hole')	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 09:51
L28	1134	@ad<="20040601" and 'flip chip' and 'semiconductor chip' with 'via'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 09:47
L29	17	@ad<="20040601" and 'flip chip' and 'interposer' and 'semiconductor chip' and 'heat spreader' and 'capacitor'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 09:51
L30	2277	@ad<="20040601" and (257/778).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 10:53
L31	966	@ad<="20040601" and (257/779).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 10:44
L32	1159	@ad<="20040601" and (257/780).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 10:44
L33	1198	@ad<="20040601" and (438/108).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 10:53

L34	1341	@ad<="20040601" and (438/118).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 10:53
L35	872	@ad<="20040601" and (438/455).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 10:54
L36	2789	@ad<="20040601" and (438/106).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 12:22
L37	3078	@ad<="20040601" and (438/612-613).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 11:10
L38	4	(("6410431") or ("6222246")).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/07 11:10
L39	2116	@ad<="20040601" and (257/774).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 11:38
L40	272	@ad<="20040601" and (438/667).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 12:21
L41	1	"6002177".PN.	USPAT; USOCR	OR	ON	2005/04/07 11:20
L42	1	"5936843".PN.	USPAT; USOCR	OR	ON	2005/04/07 11:21
L43	1	"5926951".PN.	USPAT; USOCR	OR	ON	2005/04/07 11:22
L44	1	"5936843".PN.	USPAT; USOCR	OR	ON	2005/04/07 11:22
L45	1	"5640051".PN.	USPAT; USOCR	OR	ON	2005/04/07 11:22
L46	1	"5621616".PN.	USPAT; USOCR	OR	ON	2005/04/07 11:23
L47	1	"5616517".PN.	USPAT; USOCR	OR	ON	2005/04/07 11:23

L48	233	@ad<="20040601" and 'package substrate' and 'chip' with 'via' and 'capacitor'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 11:38
L49	126	@ad<="20040601" and 'package substrate' and 'chip' with 'via' and 'capacitor' and 'resin'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 11:39
L50	188	@ad<="20040601" and (438/668). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 12:21
L51	1037	@ad<="20040601" and (438/107). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 12:22
S1	2	"20040188827"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 08:32
S2	7	akashi-tomoko.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 14:46